



Interfacial Structure-Mediated Controllable Adhesion and Assembly

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Message from the Guest Editors

This Special Issue on " Interfacial Structure-Mediated Controllable Adhesion and Assembly" aims to provide a detailed understanding of the current status and prospects of this field. It includes, but is not limited to, the following aspects:

- Development of novel interfacial structure manufacturing approaches;
- Surfaces with controllable wettabilities, including liquid-repellent surfaces;
- Adhesive, bioadhesive, and anti-bioadhesion materials;
- Interface-mediated supramolecular assembly;
- Supraparticle fabrication mediated by interfaces or surfaces.

I am pleased to invite you to submit a manuscript to this Special Issue, where we welcome original research papers and reviews on topical areas.





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Message from the Editor-in-Chief

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